

Technical Data Sheet



Product Type: No Clean Solder Paste
Product Name: Microbond® PE825
Product ID: F825 SA35-89M30

Description

F825 SA35-89M30 solder paste is a ready-to-use, homogeneous mixture with low odour characteristics, consisting of metal powder, binders, solvents, fluxes and thixotropic agents. Very high Surface insulation resistance of the flux residues. The solder paste is insensitive to humidity and temperature. Especially developed for DCB application.

Key Benefits

- Outstanding wetting
- Exceptional print to print consistency
- Min. 6 hours tack and work life

Applications

- Printing

Product Code and Alloy

Product Code					Powder Properties		
Paste	Alloy	Metal Content	*Viscosity	Powder Type	Particle Size	Alloy	Melting Point
F825	SA35	89%	M	3	25 – 45 µm	Sn96.5/Ag3.5	221 °C

*D = Dispense grade M = Print grade H = Print grade, high L = Dipping/Jetting grade, Low

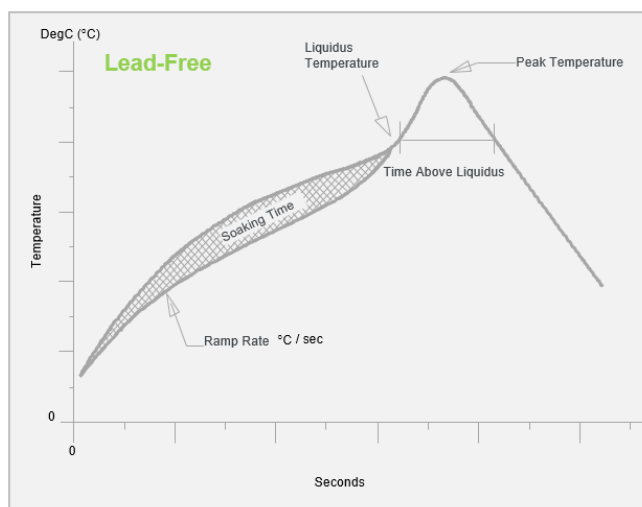
Flux Activity

Activity Level (J-STD 004)	ISO 9454-1 {DIN EN 29454-1}	Classification
RELO	1.2.3.C	No Clean/ Solvent Clean

Halogen Content

Halogen-Zero (No halogen added in the flux)
Tolerances: Halogen < 50 ppm; measured according to BS EN 14582

Recommended Reflow Profile



* Graph not drawn to scale

Recommended Profile

Average Ramp Rate	1 – 3 °C/s
Peak Temperature	20 °C (min) – 30 °C (max) above Melting Temperature
Time above liquidus	40 – 90 s
Reflow Atmosphere Type 3 – 4	Reflow in N₂ with < 1000 ppm O₂

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Cleaning Instructions

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

Storage

- Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 - 10 °C
- Store cartridges with tip pointing downwards

Paste Preparation

- Remove paste from fridge: Before opening the package, leave paste for at least 4 hours (depending on jar/ cartridge size) at room temperature, so that paste warms up
- Do not open jar/cartridge while paste is cold to prevent condensation
- Do not heat the paste beyond room temperature
- Before using of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using a stainless steel or chemically resistive plastic spatula
- Caution: When automatic stirring equipment is used, do not stir the paste longer than 2 min

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